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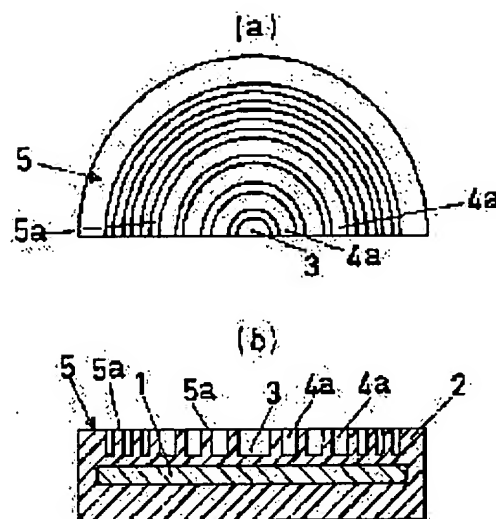
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## (54) ELECTROSTATIC CHUCK DEVICE

(57)Abstract:

PURPOSE: To provide an electrostatic chuck device capable of eliminating a temp. difference in a substrate to be treated with plasma.

CONSTITUTION: The substrate supporting face of a flat electrode 1 is covered with an insulating material 2, and a rugged face 5 is formed on the surface of the insulating material 2. The density of the recessed surface 5b, the density of the protrusion surface 5a or the depth of the recessed surface 5b in the formed rugged face 5 are changed in the surface of insulating material to distribute the electrostatic attraction to be exerted on the substrate. Reciprocity is established between the trend in the distribution of electrostatic attraction and that in the temp. distribution in the substrate by plasma treatment, and the temp. distribution is uniformized in the substrate.



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